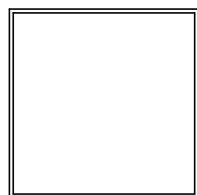
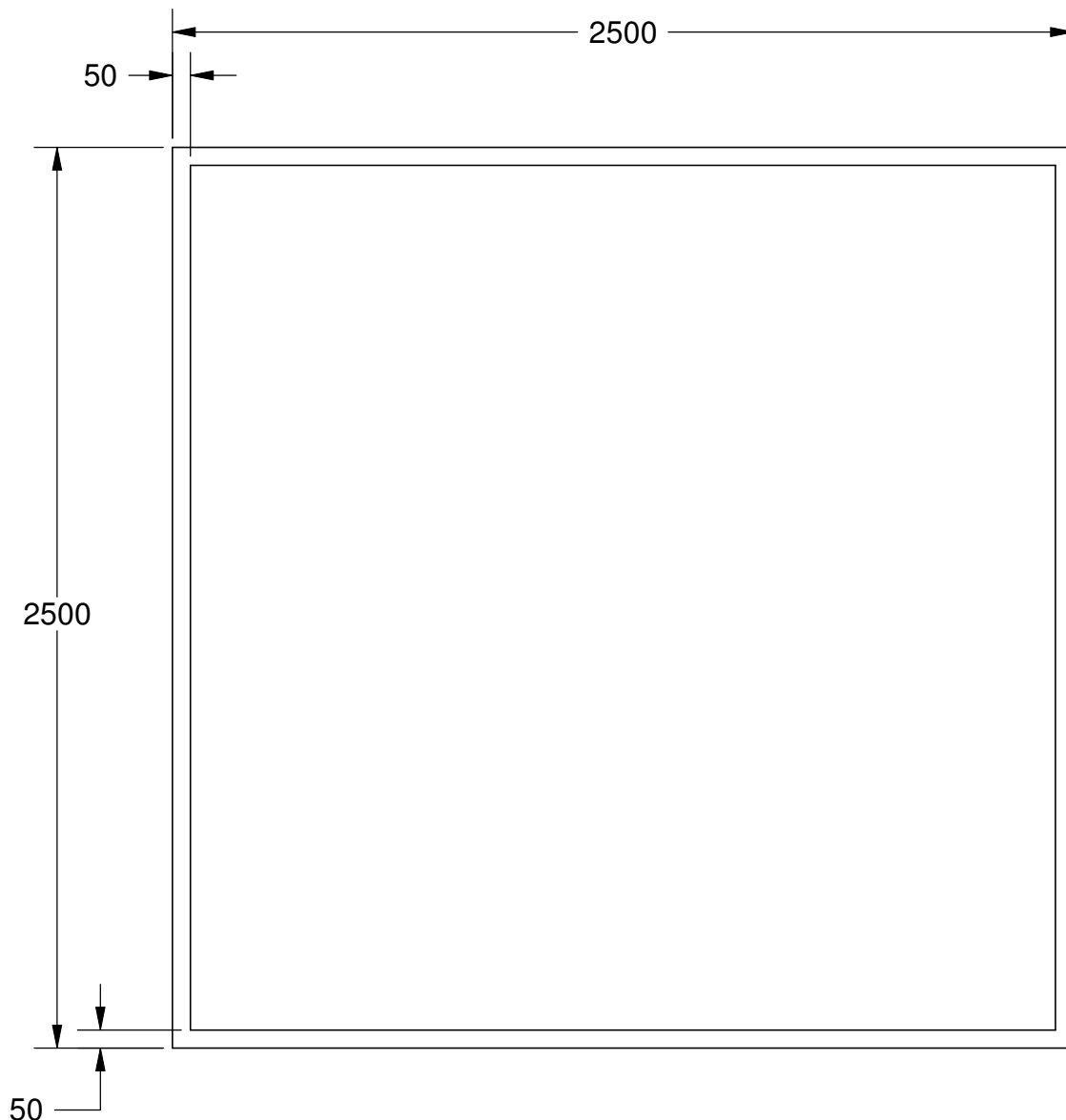


REVISIONS				
DATE	REV.	ECO	DESCRIPTION	APPROVED



SCALE 10:1

Notes: (Unless Otherwise Specified).

- 1) DIE MATERIAL IS SILICON.
- 2) DIE THICKNESS IS 250 μm (10 MIL).
- 3) METALLIZATION 1.0 μm ALUMINUM (Al) OVER 0.75 μm SiO_2 .
- 4) DIE IS WITHOUT PASSIVATION.
- 5) WIRE BONDABLE WITH GOLD (Au) OR ALUMINUM (Al) WIRE.
- 6) FULLY METALLIZED OVER ENTIRE SURFACE OF DIE.
- 7) TOLERANCE = $\pm 1 \mu\text{m}$.

DIMENSIONS IN MICRONS
1000 μm = 1.0mm

PART NUMBER SYSTEM					
TD	-	1	-	2.5	- BUS
SILICON TEST DIE	BOND PADS	DIE SIZE (mm)	FULLY METALLIZED		

TOLERANCE UNLESS NOTED	
X.XX	+/- 0.01
X.XXX	+/- 0.005
X.XXXX	+/- 0.0005
ANGLES	+/- 0.5°
ALL DIMENSIONS IN	
<input checked="" type="checkbox"/> INCHES	<input type="checkbox"/> MILLIMETERS
THIRD ANGLE PROJECTION	

APPROVALS		DATE				
DRAWN	J. HINES	5/8/2010	TITLE			
ENG			Si TEST DIE TD SERIES			
MFG			SCALE	SIZE	DRAWING NO.	REV
QA			50:1	A	152501	A
CUST			DO NOT SCALE DRAWING		SHEET 1 OF 1	
REVISED						